

# DATA SHEET

## **74HC3G07; 74HCT3G07** Buffer with open-drain outputs

Product specification

2003 Oct 15

## Buffer with open-drain outputs

## 74HC3G07; 74HCT3G07

## FEATURES

- Wide supply voltage range from 2.0 to 6.0 V
- High noise immunity
- Low power dissipation
- ESD protection:  
HBM EIA/JESD22-A114-A exceeds 2000 V  
MM EIA/JESD22-A115-A exceeds 200 V.
- Multiple package options
- Specified from  $-40$  to  $+85$  °C and  $-40$  to  $+125$  °C.

## DESCRIPTION

The 74HC3G/HCT3G07 is a high-speed Si-gate CMOS device. Specified in compliance with JEDEC standard no. 7A.

The 74HC3G/HCT3G07 provides three non-inverting buffers.

The outputs of the 74HC3G/HCT3G07 devices are open drains and can be connected to other open-drain outputs to implement active-LOW, wired-OR or active-HIGH wired-AND functions. For digital operation this device must have a pull-up resistor to establish a logic HIGH-level.

## QUICK REFERENCE DATA

GND = 0 V;  $T_{amb} = 25$  °C;  $t_r = t_f \leq 6.0$  ns.

SYMBOL	PARAMETER	CONDITIONS	TYPICAL		UNIT
			HC3G	HCT3G	
$t_{PZL}$	propagation delay nA to nY	$C_L = 50$ pF; $V_{CC} = 4.5$ V	9	11	ns
$t_{PLZ}$	propagation delay nA to nY	$C_L = 50$ pF; $V_{CC} = 4.5$ V	11	10	ns
$C_I$	input capacitance		1.5	1.5	pF
$C_{PD}$	power dissipation capacitance	notes 1 and 2	4	4	pF

## Notes

1.  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu$ W).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum (C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

$f_i$  = input frequency in MHz;

$f_o$  = output frequency in MHz;

$C_L$  = output load capacitance in pF;

$V_{CC}$  = supply voltage in Volts;

$N$  = total load switching outputs;

$\sum (C_L \times V_{CC}^2 \times f_o)$  = sum of outputs.

2. For 74HC3G07 the condition is  $V_I = \text{GND}$  to  $V_{CC}$ .  
For 74HCT3G07 the condition is  $V_I = \text{GND}$  to  $V_{CC} - 1.5$  V.

## Buffer with open-drain outputs

## 74HC3G07; 74HCT3G07

**FUNCTION TABLE**

See note 1.

INPUT	OUTPUT
nA	nY
L	L
H	Z

**Note**

- H = HIGH voltage level;  
L = LOW voltage level;  
Z = high-impedance OFF-state.

**ORDERING INFORMATION**

TYPE NUMBER	PACKAGES					
	TEMPERATURE RANGE	PINS	PACKAGE	MATERIAL	CODE	MARKING
74HC3G07DP	-40 to +125 °C	8	TSSOP8	plastic	SOT505-2	H07
74HCT3G07DP	-40 to +125 °C	8	TSSOP8	plastic	SOT505-2	T07
74HC3G07DC	-40 to +125 °C	8	VSSOP8	plastic	SOT765-1	H07
74HCT3G07DC	-40 to +125 °C	8	VSSOP8	plastic	SOT765-1	T07

**PINNING**

PIN	SYMBOL	DESCRIPTION
1	1A	data input
2	3Y	data output
3	2A	data input
4	GND	ground (0 V)
5	2Y	data output
6	3A	data input
7	1Y	data output
8	V <sub>CC</sub>	supply voltage

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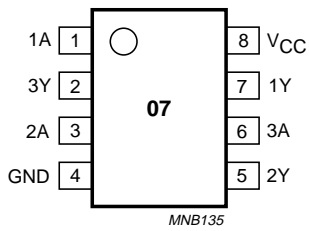


Fig.1 Pin configuration.

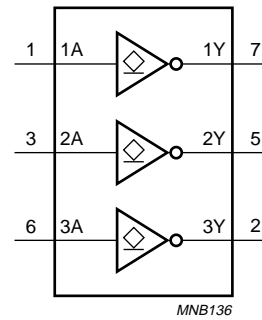


Fig.2 Logic symbol.

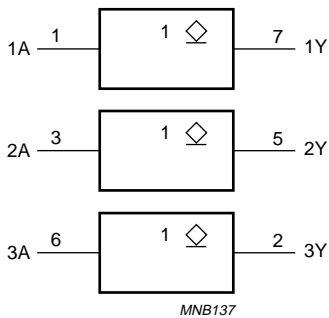


Fig.3 IEC logic symbol.

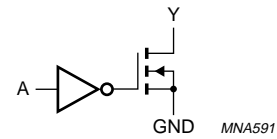


Fig.4 Logic diagram (one driver).

## Buffer with open-drain outputs

## 74HC3G07; 74HCT3G07

## RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	74HC3G07			74HCT3G07			UNIT
			MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
$V_{CC}$	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
$V_I$	input voltage		0	–	6.0	0	–	5.5	V
$V_O$	output voltage		0	–	$V_{CC}$	0	–	$V_{CC}$	V
$T_{amb}$	operating ambient temperature	see DC and AC characteristics per device	–40	+25	+125	–40	+25	+125	°C
$t_r, t_f$	input rise and fall times	$V_{CC} = 2.0$ V	–	–	1000	–	–	–	ns
		$V_{CC} = 4.5$ V	–	6.0	500	–	6.0	500	ns
		$V_{CC} = 6.0$ V	–	–	400	–	–	–	ns

## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134); voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CC}$	supply voltage		–0.5	+7.0	V
$I_{IK}$	input diode current	$V_I < -0.5$ V or $V_I > V_{CC} + 0.5$ V	–	±20	mA
$I_{OK}$	output diode current	$V_O < -0.5$ V	–	–20	mA
$V_O$	output voltage	active mode; note 1	–0.5	$V_{CC} + 0.5$	V
		high-impedance mode; note 1	–0.5	7.0	V
$I_O$	output sink current	$-0.5$ V < $V_O$ < 7.0 V	–	–25	mA
$I_{CC}$	$V_{CC}$ or GND current	note 1	–	50	mA
$T_{stg}$	storage temperature		–65	+150	°C
$P_D$	power dissipation	$T_{amb} = -40$ to $+125$ °C; note 2	–	300	mW

## Notes

1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. Above 110 °C the value of  $P_D$  derates linearly with 8 mW/K.

## Buffer with open-drain outputs

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## DC CHARACTERISTICS

## Type 74HC3G07

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP. <sup>(1)</sup>	MAX.	UNIT
		OTHER	V <sub>CC</sub> (V)				
<b>T<sub>amb</sub> = -40 to +85 °C</b>							
V <sub>IH</sub>	HIGH-level input voltage		2.0	1.5	1.2	–	V
			4.5	3.15	2.4	–	V
			6.0	4.2	3.2	–	V
V <sub>IL</sub>	LOW-level input voltage		2.0	–	0.8	0.5	V
			4.5	–	2.1	1.35	V
			6.0	–	2.8	1.8	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = 20 µA	2.0	–	0	0.1	V
		I <sub>O</sub> = 20 µA	4.5	–	0	0.1	V
		I <sub>O</sub> = 20 µA	6.0	–	0	0.1	V
		I <sub>O</sub> = 4.0 mA	4.5	–	0.15	0.33	V
		I <sub>O</sub> = 5.2 mA	6.0	–	0.16	0.33	V
I <sub>LI</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND	6.0	–	–	±1.0	µA
I <sub>oz</sub>	3-state output OFF current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>O</sub> = V <sub>CC</sub> or GND	6.0	–	–	±5.0	µA
I <sub>CC</sub>	quiescent supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0	6.0	–	–	10	µA
<b>T<sub>amb</sub> = -40 to +125 °C</b>							
V <sub>IH</sub>	HIGH-level input voltage		2.0	1.5	–	–	V
			4.5	3.15	–	–	V
			6.0	4.2	–	–	V
V <sub>IL</sub>	LOW-level input voltage		2.0	–	–	0.5	V
			4.5	–	–	1.35	V
			6.0	–	–	1.8	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = 20 µA	2.0	–	–	0.1	V
		I <sub>O</sub> = 20 µA	4.5	–	–	0.1	V
		I <sub>O</sub> = 20 µA	6.0	–	–	0.1	V
		I <sub>O</sub> = 4.0 mA	4.5	–	–	0.4	V
		I <sub>O</sub> = 5.2 mA	6.0	–	–	0.4	V
I <sub>LI</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND	6.0	–	–	±1.0	µA
I <sub>oz</sub>	3-state output OFF current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>O</sub> = V <sub>CC</sub> or GND	6.0	–	–	±10	µA
I <sub>CC</sub>	quiescent supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0	6.0	–	–	20	µA

**Note**

1. All typical values are measured at T<sub>amb</sub> = 25 °C.

## Buffer with open-drain outputs

## 74HC3G07; 74HCT3G07

**Type 74HCT3G07**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP. <sup>(1)</sup>	MAX.	UNIT
		OTHER	V <sub>CC</sub> (V)				
<b>T<sub>amb</sub> = -40 to +85 °C</b>							
V <sub>IH</sub>	HIGH-level input voltage		4.5 to 5.5	2.0	1.6	–	V
V <sub>IL</sub>	LOW-level input voltage		4.5 to 5.5	–	1.2	0.8	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = 20 μA	4.5	–	0	0.1	V
		I <sub>O</sub> = 4.0 mA	4.5	–	0.15	0.33	V
I <sub>LI</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5	–	–	±1.0	μA
I <sub>OZ</sub>	3-state output OFF current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>O</sub> = V <sub>CC</sub> or GND	5.5	–	–	±5.0	μA
I <sub>CC</sub>	quiescent supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0	5.5	–	–	10	μA
ΔI <sub>CC</sub>	additional supply current per input	V <sub>I</sub> = V <sub>CC</sub> – 2.1 V; I <sub>O</sub> = 0	4.5 to 5.5	–	–	375	μA
<b>T<sub>amb</sub> = -40 to +125 °C</b>							
V <sub>IH</sub>	HIGH-level input voltage		4.5 to 5.5	2.0	–	–	V
V <sub>IL</sub>	LOW-level input voltage		4.5 to 5.5	–	–	0.8	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = 20 μA	4.5	–	–	0.1	V
		I <sub>O</sub> = 4.0 mA	4.5	–	–	0.4	V
I <sub>LI</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5	–	–	±1.0	μA
I <sub>OZ</sub>	3-state output OFF current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>O</sub> = V <sub>CC</sub> or GND	5.5	–	–	±10	μA
I <sub>CC</sub>	quiescent supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0	5.5	–	–	20	μA
ΔI <sub>CC</sub>	additional supply current per input	V <sub>I</sub> = V <sub>CC</sub> – 2.1 V; I <sub>O</sub> = 0	4.5 to 5.5	–	–	410	μA

**Note**1. All typical values are measured at T<sub>amb</sub> = 25 °C.

## Buffer with open-drain outputs

## 74HC3G07; 74HCT3G07

## AC CHARACTERISTICS

## Type 74HC3G07

GND = 0 V;  $t_r = t_f \leq 6.0$  ns;  $C_L = 50$  pF.

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP. <sup>(1)</sup>	MAX.	UNIT
		WAVEFORMS	V <sub>CC</sub> (V)				
<b>T<sub>amb</sub> = -40 to +85 °C</b>							
t <sub>PZL</sub>	propagation delay nA to nY	see Figs 5 and 6	2.0	–	25	95	ns
			4.5	–	9	19	ns
			6.0	–	7	16	ns
t <sub>PLZ</sub>	propagation delay nA to nY	see Figs 5 and 6	2.0	–	25	95	ns
			4.5	–	11	23	ns
			6.0	–	10	23	ns
t <sub>THL</sub>	output transition time	see Figs 5 and 6	2.0	–	18	95	ns
			4.5	–	6	19	ns
			6.0	–	5	16	ns
<b>T<sub>amb</sub> = -40 to +125 °C</b>							
t <sub>PZL</sub>	propagation delay nA to nY	see Figs 5 and 6	2.0	–	–	125	ns
			4.5	–	–	25	ns
			6.0	–	–	20	ns
t <sub>PLZ</sub>	propagation delay nA to nY	see Figs 5 and 6	2.0	–	–	125	ns
			4.5	–	–	30	ns
			6.0	–	–	26	ns
t <sub>THL</sub>	output transition time	see Figs 5 and 6	2.0	–	–	125	ns
			4.5	–	–	25	ns
			6.0	–	–	20	ns

## Note

1. All typical values are measured at T<sub>amb</sub> = 25 °C.

## Buffer with open-drain outputs

## 74HC3G07; 74HCT3G07

**Type 74HCT3G07**GND = 0 V;  $t_r = t_f \leq 6.0$  ns;  $C_L = 50$  pF.

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP. <sup>(1)</sup>	MAX.	UNIT
		WAVEFORMS	V <sub>CC</sub> (V)				
<b>T<sub>amb</sub> = -40 to +85 °C</b>							
t <sub>PZL</sub>	propagation delay nA to nY	see Figs 5 and 6	4.5	–	11	27	ns
t <sub>PLZ</sub>	propagation delay nA to nY	see Figs 5 and 6	4.5	–	10	26	ns
t <sub>THL</sub>	output transition time	see Figs 5 and 6	4.5	–	6	19	ns
<b>T<sub>amb</sub> = -40 to +125 °C</b>							
t <sub>PZL</sub>	propagation delay nA to nY	see Figs 5 and 6	4.5	–	–	32	ns
t <sub>PLZ</sub>	propagation delay nA to nY	see Figs 5 and 6	4.5	–	–	31	ns
t <sub>THL</sub>	output transition time	see Figs 5 and 6	4.5	–	–	22	ns

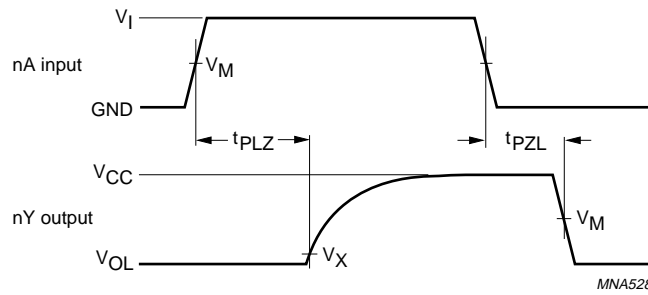
**Note**

1. All typical values are measured at T<sub>amb</sub> = 25 °C.

Buffer with open-drain outputs

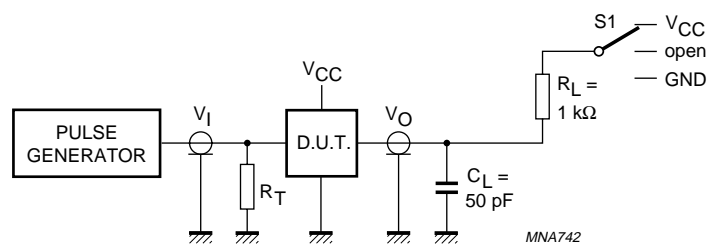
74HC3G07; 74HCT3G07

AC WAVEFORMS



For 74HC3G07:  $V_M = 50\%$ ;  $V_1 = \text{GND to } V_{CC}$ .  
 For 74HCT3G07:  $V_M = 1.3 \text{ V}$ ;  $V_1 = \text{GND to } 3.0 \text{ V}$ .  
 For 74HC3G07 and 74HCT3G07:  $V_X = 0.1 \times V_{CC}$ .

Fig.5 The input (nA) to output (nY) propagation delays and transition times.



TEST	S1
$t_{PLH}/t_{PHL}$	open
$t_{PLZ}/t_{PZL}$	$V_{CC}$
$t_{PHZ}/t_{PZH}$	GND

Definitions for test circuit:  
 $R_L$  = Load resistor.  
 $C_L$  = load capacitance including jig and probe capacitance.  
 $R_T$  = termination resistance should be equal to the output impedance  $Z_o$  of the pulse generator.

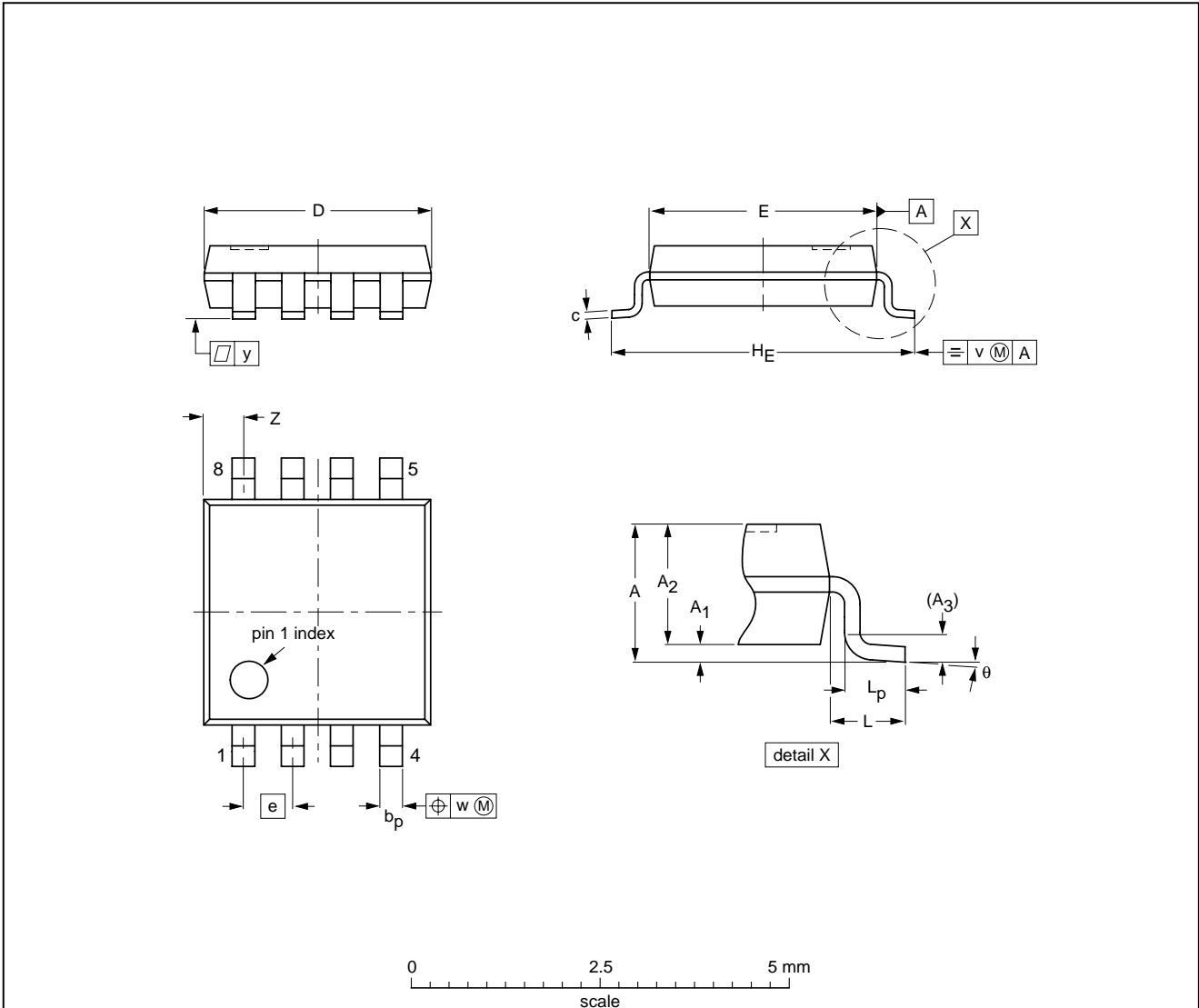
Fig.6 Load circuitry for switching times.

Buffer with open-drain outputs

74HC3G07; 74HCT3G07

PACKAGE OUTLINES

TSSOP8: plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm SOT505-2



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	v	w	y	z <sup>(1)</sup>	θ
mm	1.1	0.15 0.00	0.95 0.75	0.25	0.38 0.22	0.18 0.08	3.1 2.9	3.1 2.9	0.65	4.1 3.9	0.5	0.47 0.33	0.2	0.13	0.1	0.70 0.35	8° 0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

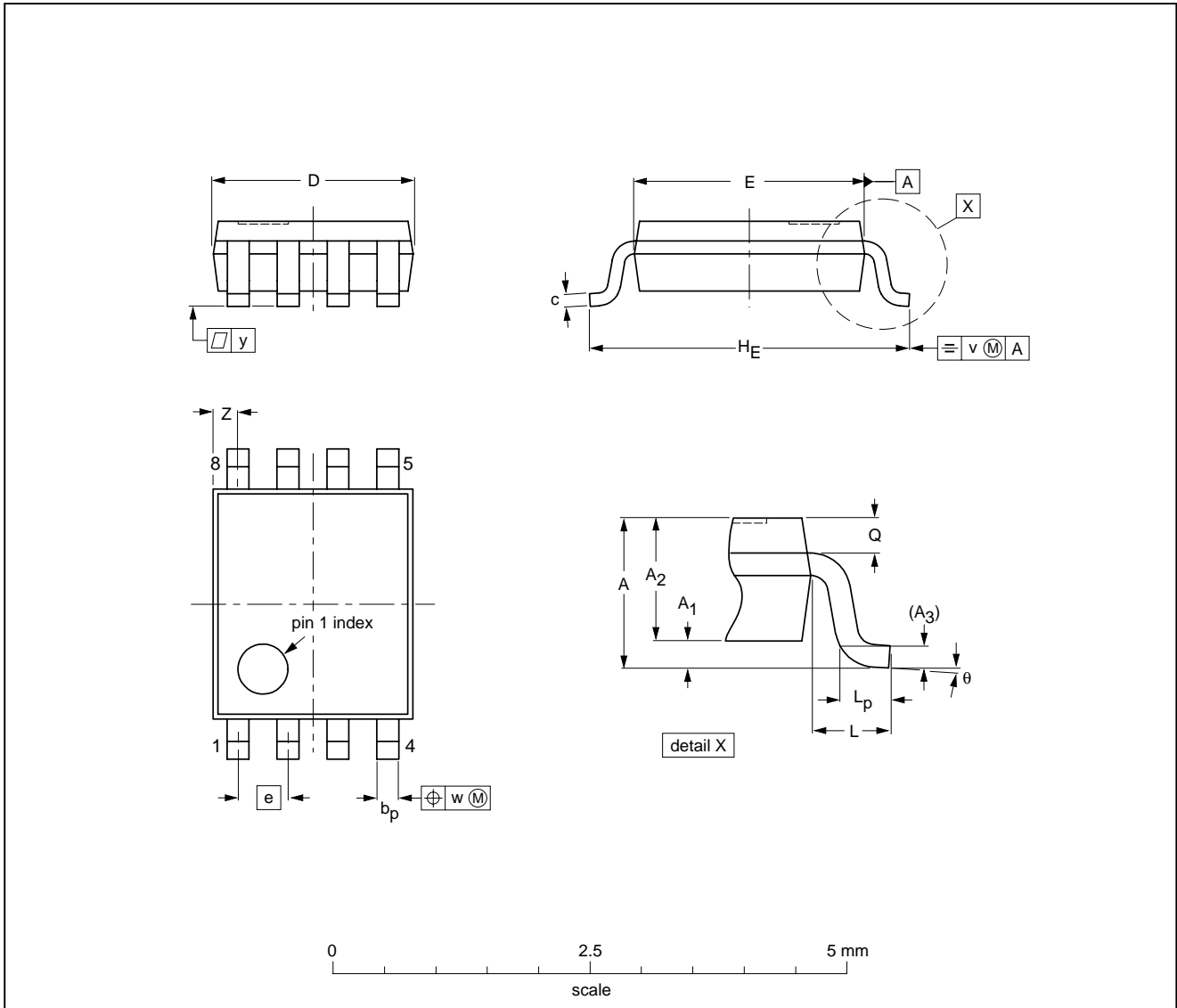
OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT505-2		---			02-01-16

Buffer with open-drain outputs

74HC3G07; 74HCT3G07

VSSOP8: plastic very thin shrink small outline package; 8 leads; body width 2.3 mm

SOT765-1



**DIMENSIONS (mm are the original dimensions)**

UNIT	A <sub>max.</sub>	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(2)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	1	0.15 0.00	0.85 0.60	0.12	0.27 0.17	0.23 0.08	2.1 1.9	2.4 2.2	0.5	3.2 3.0	0.4	0.40 0.15	0.21 0.19	0.2	0.13	0.1	0.4 0.1	8° 0°

**Notes**

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT765-1		MO-187				02-06-07

## Buffer with open-drain outputs

## 74HC3G07; 74HCT3G07

## DATA SHEET STATUS

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)(3)</sup>	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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